US00D791091S

(12) **United States Design Patent**
**Okada et al.**

(10) **Patent No.: US D791,091 S**
(45) **Date of Patent: ** Jul. 4, 2017**

(54) **PATTERN WAFER**

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(**) Term: **15 Years**

(21) Appl. No.: **29/569,263**

(22) Filed: **Jun. 24, 2016**

(30) **Foreign Application Priority Data**

Dec. 28, 2015 (JP) ................................ 2015-029186

(51) **LOC (10) Cl.** ................................................ **13-03**
(52) **U.S. Cl.**
USPC ........................................................ **D13/182**
(58) **Field of Classification Search**
USPC .......................................... D13/182; D6/309
CPC ......... C30B 25/02; C30B 25/04; C30B 25/12; C30B 25/18; C30B 25/186; C30B 25/20; H01L 21/2018; H01L 21/2003; H01L 21/02367; H01L 21/0237; H01L 21/02428; H01L 21/0243; H01L 21/02433; H01L 21/02436; H01L 21/31116; H01L 21/32139; H01L 21/31144; H01L 21/0337; H01L 21/31138; H01L 21/02439; H01L 21/3213; H01L 21/32131; H01L 21/32133; H01L 21/32135; H01L 21/823807; H01L 21/84; H01L 21/31055; H01L 21/31053; H01L 21/76819; H01L 21/31111; H01L 33/16; H01L 29/02; H01L 29/04; H01L 29/045; H01L 29/06; H01L 29/0603; H01L 29/66765; H01L 29/66757; H01L 27/1203; H01L 27/1218; H01L 27/1222; H01S 5/3202

See application file for complete search history.

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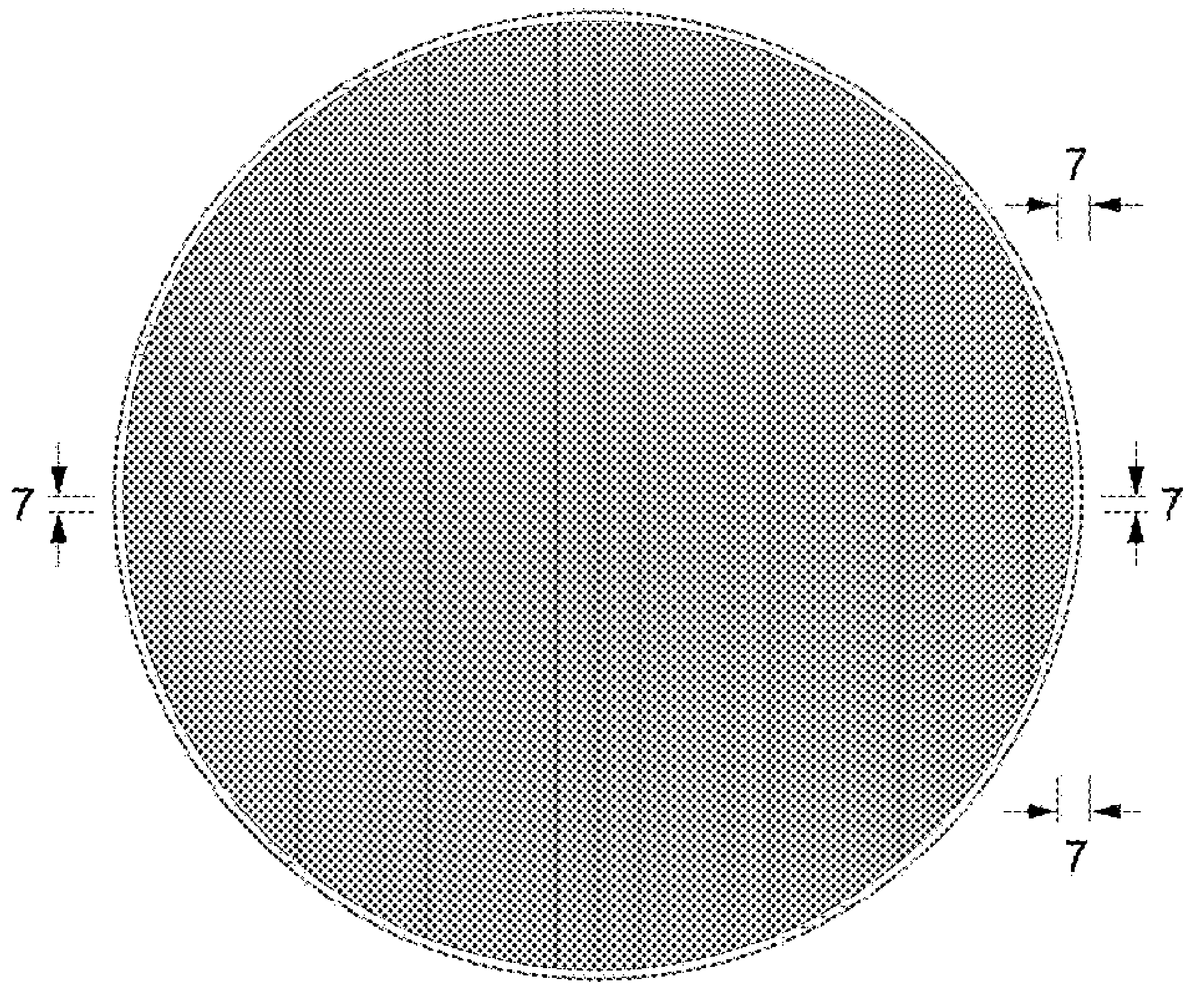
(57) **CLAIM**

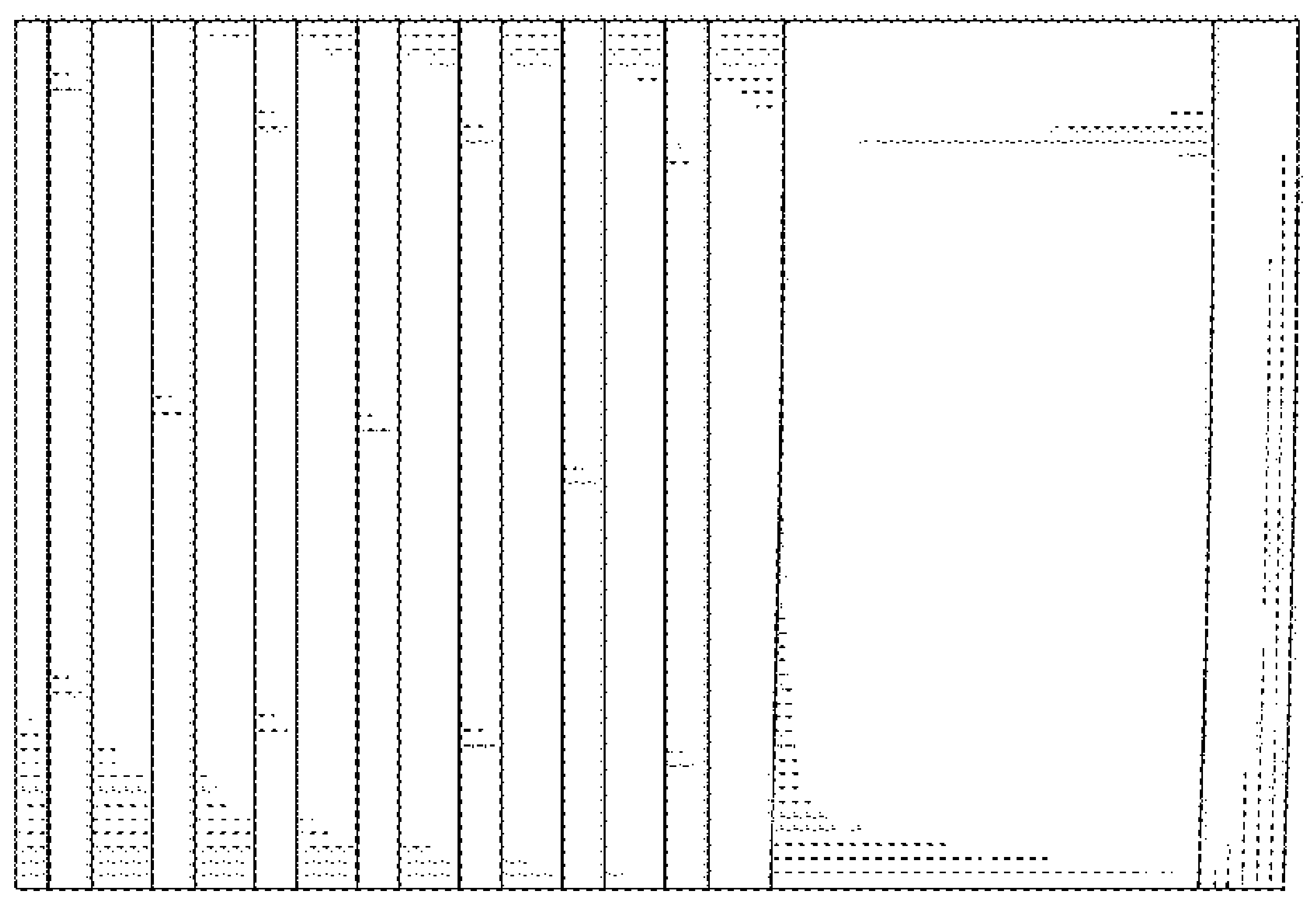
The ornamental design for a pattern wafer, as shown and described.

**DESCRIPTION**

FIG. **1** is a front elevational view of a pattern wafer, showing our new design;
FIG. **2** is a rear elevational view thereof;
FIG. **3** is a left side elevational view thereof;
FIG. **4** is a right side elevational view thereof;
FIG. **5** is a top plan view thereof;
FIG. **6** is a bottom plan view thereof;
FIG. **7** is an enlarged front portion view taken along line **7-7** in FIG. **1**;
FIG. **8** is an enlarged bottom portion view taken along line **8-8** in FIG. **6**; and,
FIG. **9** is a top perspective view of FIG. **7**.

**1 Claim, 5 Drawing Sheets**





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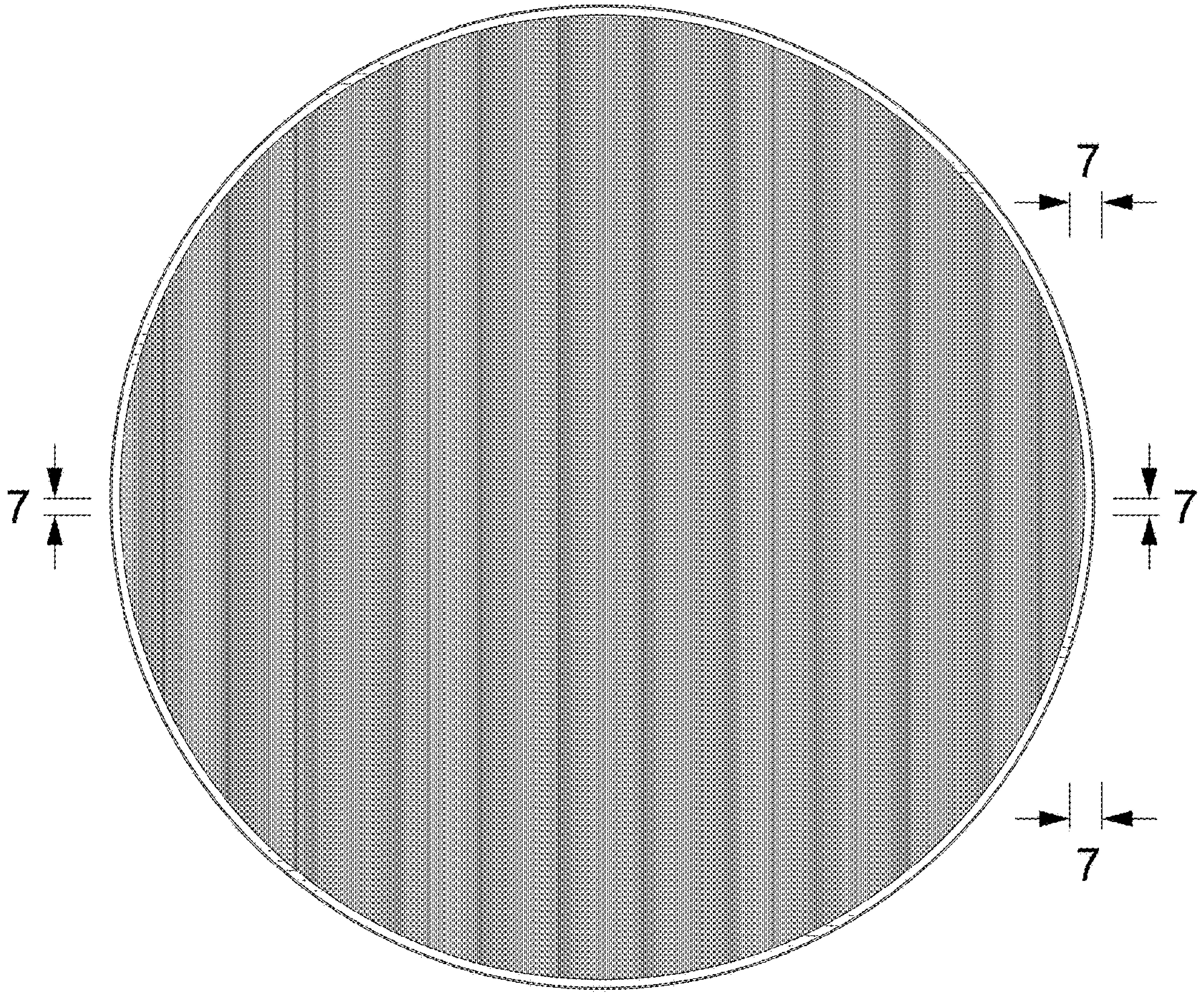

FIG. 1

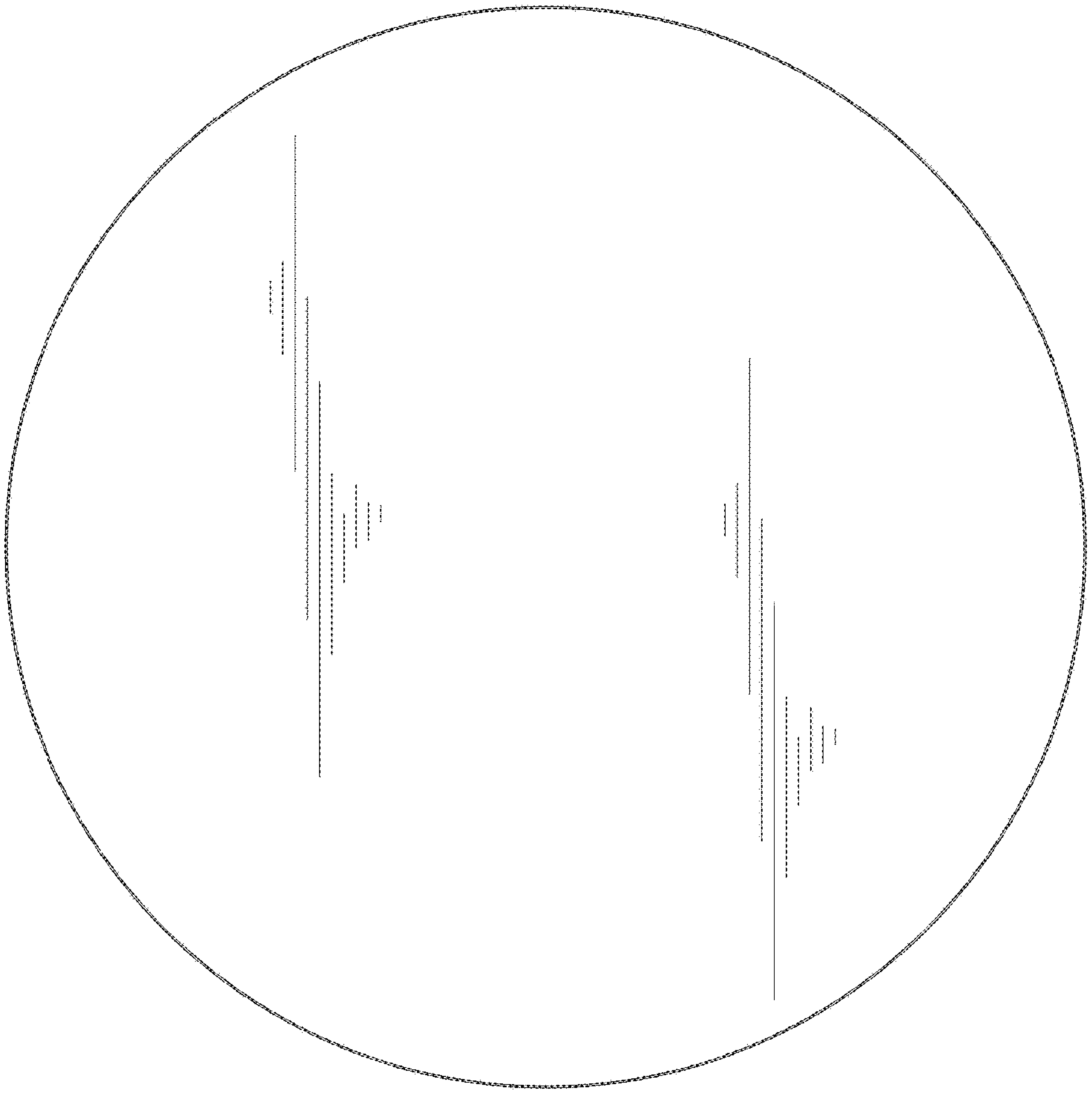

FIG. 2

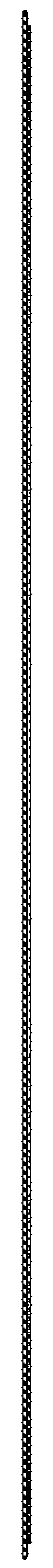

FIG. 3

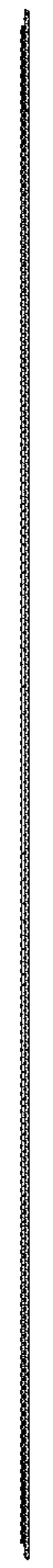

FIG. 4

FIG. 5

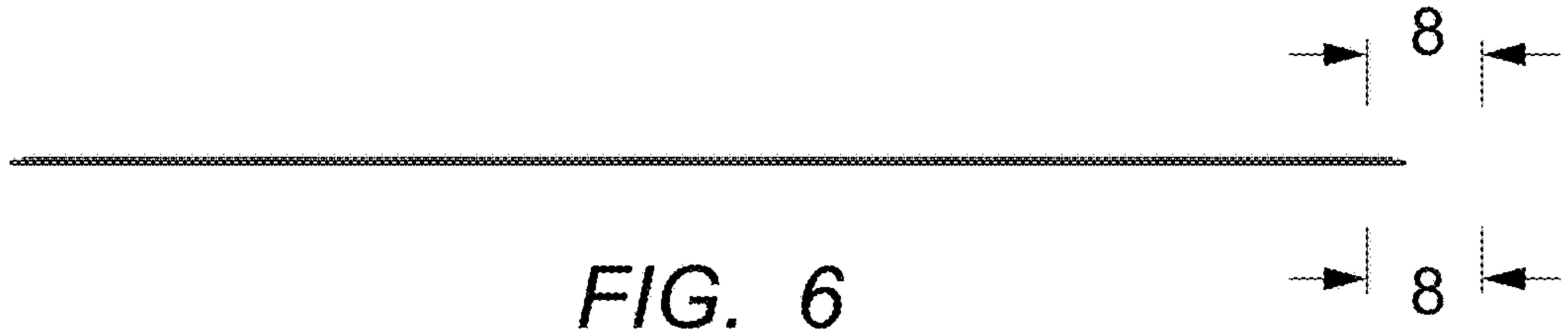

FIG. 6

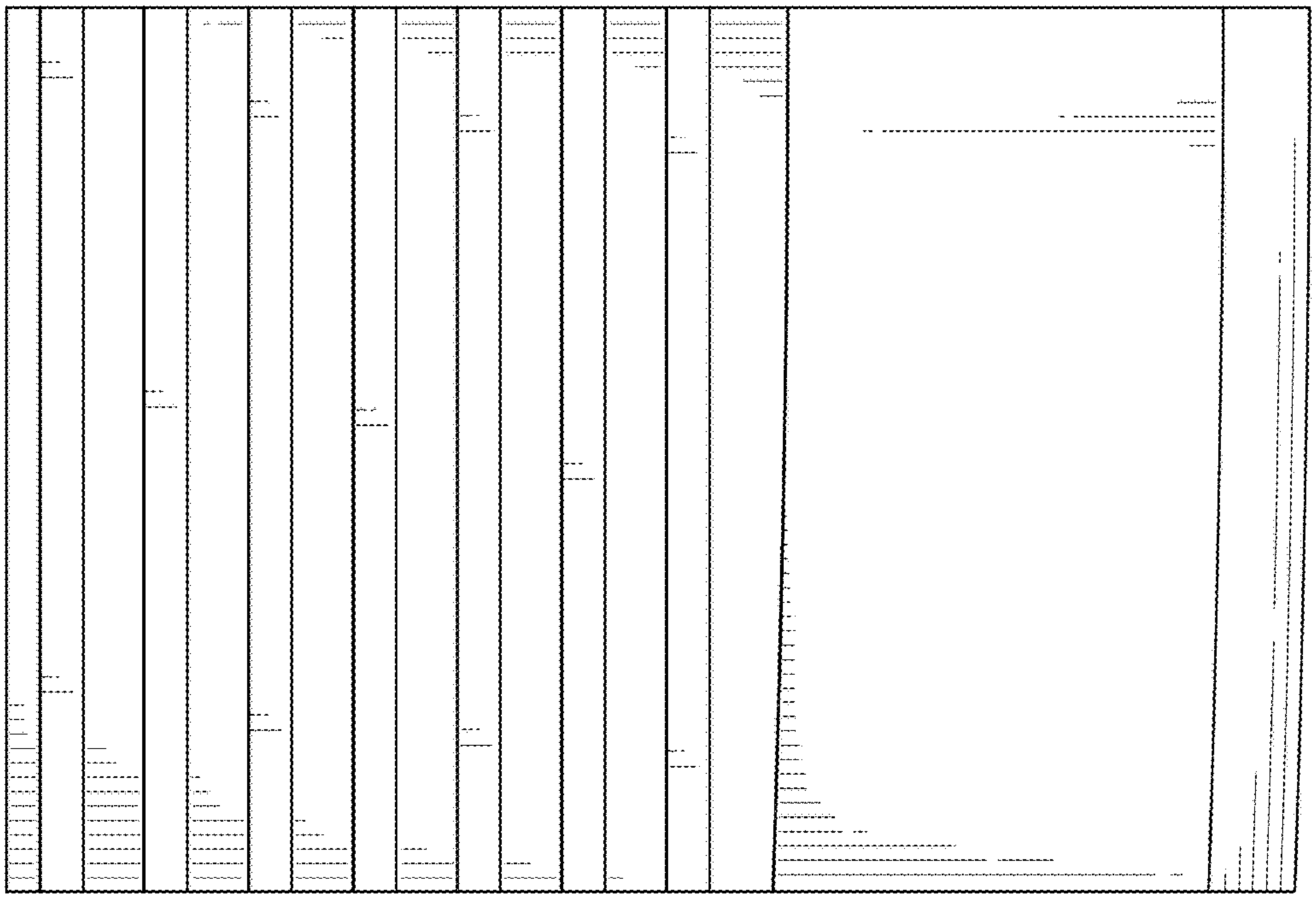

FIG. 7

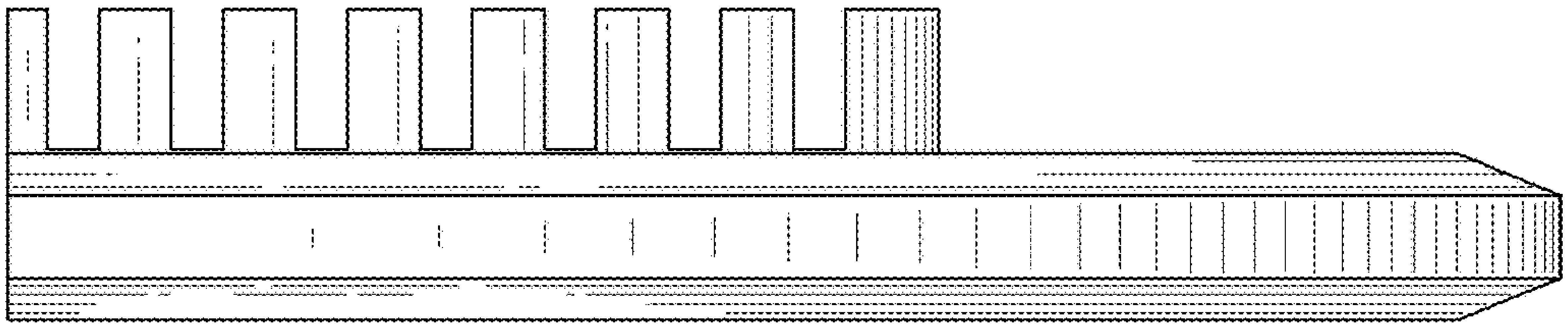

FIG. 8

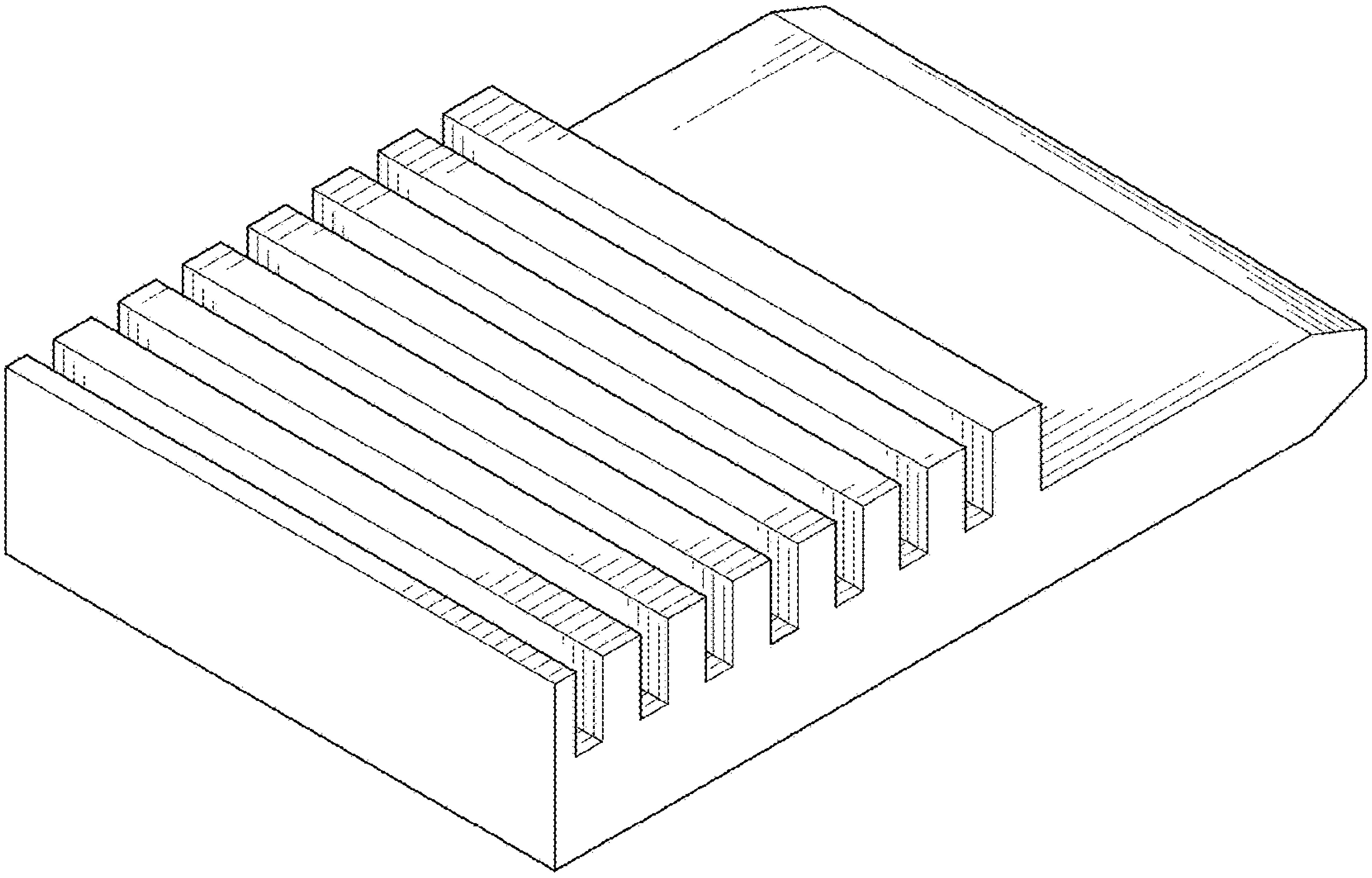

FIG. 9